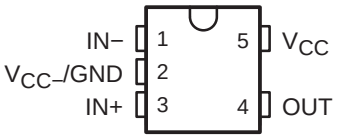
SLVS238E − AUGUST 1999 − REVISED SEPTEMBER 2004

- **Single Supply or Dual Supplies**
- **Wide Range of Supply Voltage . . . 2 V to 36 V**
- **Low Supply-Current Drain Independent of Supply Voltage . . . 0.4 mA Typ**
- **Low Input Bias Current . . . 25 nA Typ**
- **Low Input Offset Voltage . . . 2 mV Typ**
- **Common-Mode Input Voltage Range Includes Ground**
- **Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V**
- **Low Output Saturation Voltage**
- **Output Compatible With TTL, MOS, and CMOS**

DBV PACKAGE
(TOP VIEW)



description/ordering information

This device consists of a single voltage comparator that is designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible if the difference between the two supplies is 2 V to 36 V and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The output can be connected to other open-collector outputs to achieve wired-AND relationships.

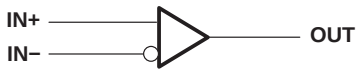
ORDERING INFORMATION

T_A	V_{IO}(max) at 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 85°C	5 mV	SOT-23 (DBV)	Reel of 3000	TL331IDBVR	T1I_
			Reel of 250	TL331IDBVT	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ DBV: The actual top-side marking has one additional character that designates the assembly/test site.

logic diagram



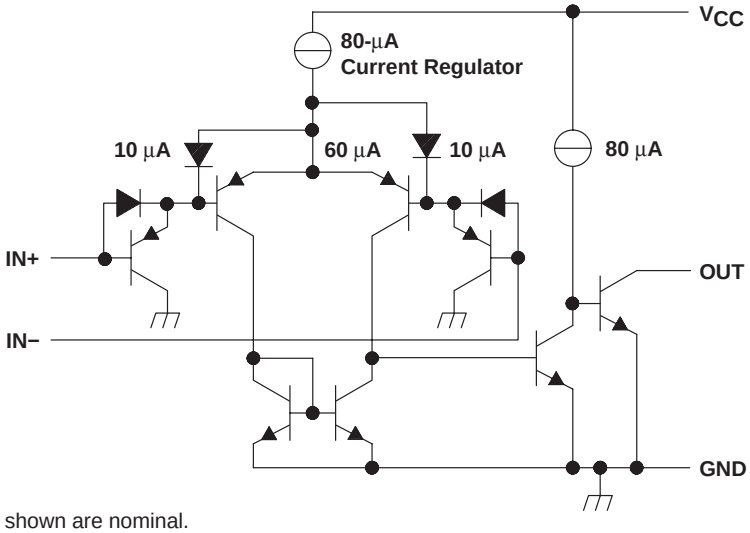


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schematic



COMPONENT COUNT	
Epi-FET	1
Diodes	2
Resistors	1
Transistors	20

Current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 36 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±36 V
Input voltage range, V_I (either input) . . . . . −0.3 V to 36 V
Output voltage, V_O . . . . . 36 V
Output current, I_O . . . . . 20 mA
Duration of output short-circuit to ground (see Note 3) . . . . . Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5) . . . . . 206°C/W
Operating virtual junction temperature, T_J . . . . . 150°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to the network ground.
2. Differential voltages are at IN+ with respect to IN−.
3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	V_{CC} = 5 V to 30 V, V_O = 1.4 V, $V_{IC} = V_{IC(min)}$		25°C		2	5	mV
				−40°C to 85°C			9	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		5	50	nA
				−40°C to 85°C			250	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		−25	−250	nA
				−40°C to 85°C			−400	
V_{ICR}	Common-mode input voltage range‡			25°C	0 to V_{CC} − 1.5			V
				−40°C to 85°C	0 to V_{CC} − 1.5			
A_{VD}	Large-signal differential voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, $R_L \geq 15\ k\Omega$ to V_{CC}		25°C	50	200		V/mV
I_{OH}	High-level output current	V_{OH} = 5 V,	V_{ID} = 1 V	25°C		0.1	50	nA
		V_{OH} = 30 V,	V_{ID} = 1 V	−40°C to 85°C			1	µA
V_{OL}	Low-level output voltage	I_{OL} = 4 mA,	V_{ID} = −1 V	25°C		150	400	mV
				−40°C to 85°C			700	
I_{OL}	Low-level output current	V_{OL} = 1.5 V,	V_{ID} = 1 V	25°C	6			mA
I_{CC}	Supply current	R_L = ∞,	V_{CC} = 5 V	25°C		0.4	0.7	mA

† All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
‡ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} − 1.5 V, but either or both inputs can go to 30 V without damage.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		TYP	UNIT
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF§ (see Note 6)	100-mV input step with 5-mV overdrive	1.3	µs
		TTL-level input step	0.3	

§ C_L includes probe and jig capacitance.
NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TL331IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

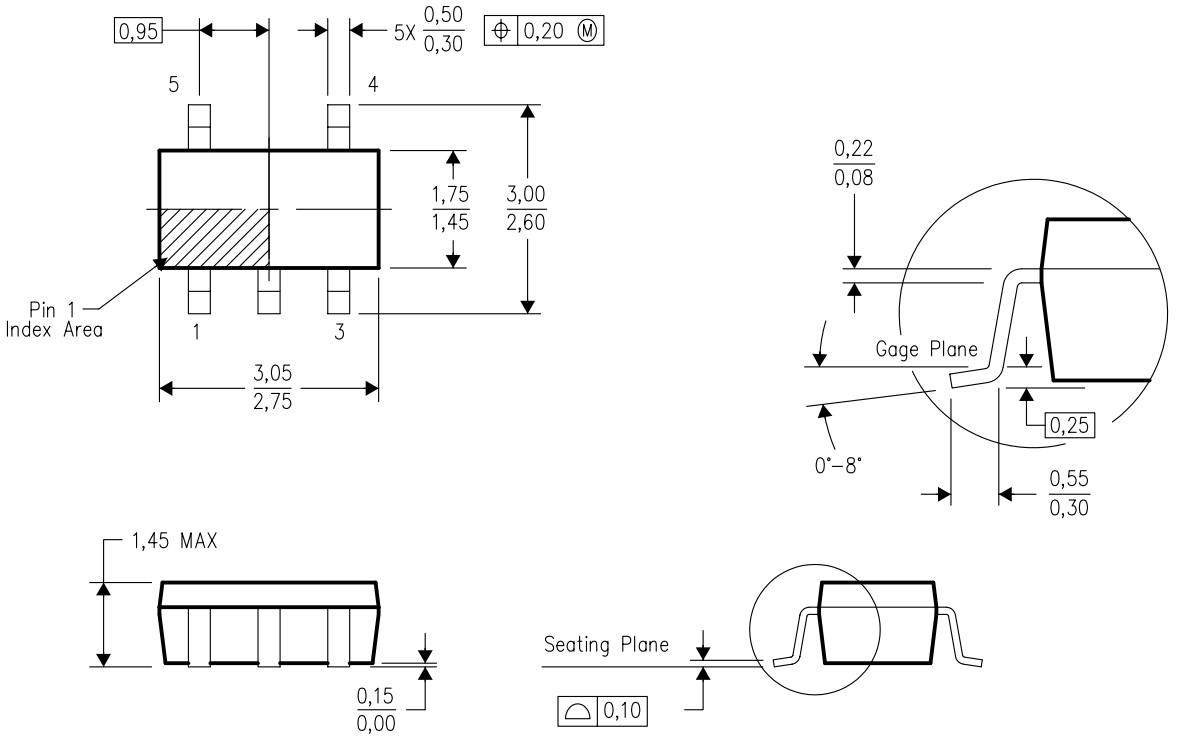
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4073253–4/K 03/2006

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–178 Variation AA.

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